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3次元実装モジュールの検討

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Examination on the 3D Assembly Module

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Abstract

We have presented R&D progress of our Three Dimensional Assembly Module called TZ-CSP (Tape Z-axis Chip Size Package) in our previous papers. In this presentation, we would like to present you improvement in assembly techniques and refinement in design parameters we have made in order to mass-produce TZ-CSP. Specific improvements are made to the key processes in TZ-CSP production such as tooling method and connecting method for inter-layer connection lead. Also, we have evaluated status of further functional improvements caused by SIP (System In Package) and Lead free solder. We also would like to present you the concept of trend towards SIP.

Key Words: *3D-Module, High-Density Assembly, Multiple Layered in Z-Axis, System In Package, Tape Automated Bonding (TAB)*